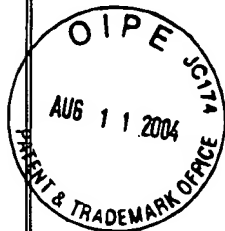


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ATTY. DOCKET NO.
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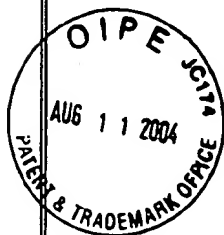
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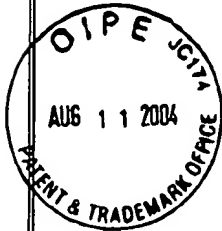
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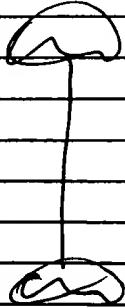
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


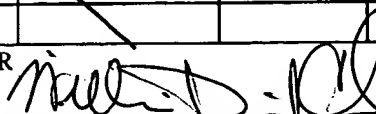
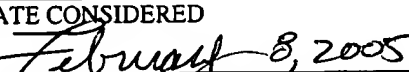
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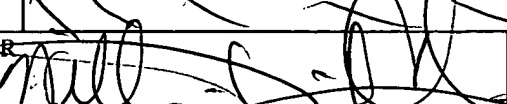
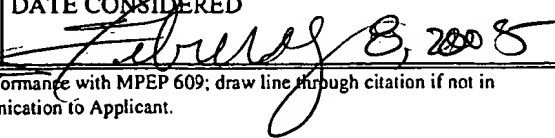
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			APPLICANT SHANMUGASUNDRAM et al.			
			FILING DATE August 31, 2001		GROUP 2823	
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				APPLICANT SHANMUGASUNDRAM et al.				FILING DATE August 31, 2001	
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